



Knowledge in Process

For Immediate Release

**Speedline to Present Webinar on Printing Solder
Paste for Flip Chip Bumps**

FRANKLIN, MASS – June 6, 2007 – Each month, Speedline Technologies offers a webinar free of charge on a topic relevant to process engineers in OEM and contract electronics manufacturing. On Thursday, July 19, 2007, a webcast will be offered on stencil printing solder paste for the formation of solder bumps. The presentation lasts one hour and commences at 11:00 am Eastern time.

A common method used to create bumps on flip chips is printing solder paste directly on to the silicon wafers, followed by reflow soldering. Printing solder paste for flip chip bumps requires a very accurate, repeatable printing process. The correct volume of solder paste must be printed on each input/output pad of the wafer to ensure a consistent flip chip bump height. If this height is not precisely controlled, defects in the attachment of the flip chip to the substrate will occur.

This webinar will review all aspects of the bump printing process including stencil design, solder paste selection, fixturing and printing parameters. In addition, optimization of the related reflow soldering process will be discussed.

To register for the Speedline webcast seminars, go to www.speedlinetech.com/seminars and complete the short contact information form. After registration, an email is sent with the website access address and the toll-free phone conference number. No special hardware or software is required, just high speed internet access and a telephone. A detailed schedule is provided on the web page above providing monthly topics and information on the webinar schedule for the remainder of 2007.

###

About Speedline Technologies

Speedline Technologies is the global leader in process knowledge, services and manufacture of capital equipment used in printed circuit board assembly and semiconductor industries. Based in Franklin, Massachusetts, USA, the company markets five best-in-class brands: Accel microelectronics cleaning equipment; Camalot dispensing systems; Electrovert wave soldering, reflow soldering and cleaning equipment; MPM stencil and screen printing systems; and Protect global services, support and training solutions. Speedline Technologies was named Frost & Sullivan's "2005 Surface Mount Technology Company of the Year," and has earned their "2006 Competitive Strategy Leadership Award."

For more information about Speedline Technologies visit www.speedlinetech.com or contact Speedline at:

- USA: Speedline Technologies, 16 Forge Park, Franklin, MA 02038. Tel: +1-508-520-0083. Fax: +1-508-520-2288. Email: info@speedlinetech.com.
- Europe: Speedline Technologies GmbH, Im Gefierth 14, 63303 Dreieich, Germany. Tel: +49 (0) 6103/832-0. Fax: +49 (0) 6102/832-299. Email: info.europe@speedlinetech.com.
- Asia: Speedline Technologies Asia Pte Ltd, 150 Kampong Ampat, #05-08 KA Centre, Singapore 368324. Tel: +65 6286-6635. Fax: +65 6289-9411. Email: asiamarketing@speedlinetech.com.

Speedline Contact:

Keith Favre, VP Marketing and Business Development
kfavre@speedlinetech.com
508-541-4877

Media Contact:

Bob Schreitmueller
Apogee Business Consulting, LLC
bob@ReachApogee.com